

ABSTRACT

A semiconductor module (A1) comprises a semiconductor device (10) provided with a semiconductor chip, and a
5 conductive cover (6) for electromagnetic shielding bonded to the semiconductor device (10) via an adhesive coat (8). The conductive cover (6) includes a surface facing the adhesive coat (8), and the surface is formed with a convex portion (6a) protruding toward the adhesive coat (8). Around the convex
10 portion (6a), a space (7) is formed for filling in adhesive to form the adhesive coat (8).

(Fig. 2)